



## Final Product Change Notification

202303003F01 : TFME-T Assembly Site Expansion for Select C90TFS Technology LQFP Devices

**Note:** This notice is NXP Company Proprietary.

**Issue Date:** Apr 21, 2023 **Effective date:** Jul 20, 2023

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### Change Category

<input type="checkbox"/> Wafer Fab Process	<input type="checkbox"/> Assembly Process	<input type="checkbox"/> Product Marking	<input type="checkbox"/> Test Process	<input type="checkbox"/> Design
<input type="checkbox"/> Wafer Fab Materials	<input checked="" type="checkbox"/> Assembly Materials	<input type="checkbox"/> Mechanical Specification	<input type="checkbox"/> Test Equipment	<input type="checkbox"/> Errata
<input type="checkbox"/> Wafer Fab Location	<input checked="" type="checkbox"/> Assembly Location	<input type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/> Test Location	<input type="checkbox"/> Electrical spec./Test coverage
<input type="checkbox"/> Firmware	<input type="checkbox"/> Other			

## PCN Overview

### Description

NXP Semiconductors announces the assembly site expansion for the S32K148 and S32K144 devices associated with this notification from the current NXP-ATKL, Kuala Lumpur, Malaysia and NXP-ATTJ, Tianjin, China assembly facility to Tongfu Tongke (Nantong) Microelectronics (TFME-T), Nantong, China, to meet increasing demand.

TongFu Tongke (Nantong) Microelectronics Co., LTD (TFME) completed new site TFME-T for production capacity expansion. TFME-T is located in Nantong City, China, 14km from TFME-HQ, with a production area consisting of 3 buildings totaling 97,900SM. Building 1 with 34,521SM is dedicated solely for Automotive LQFP, with general production launched April 2022.

TFME-T follows identical quality systems as TFME-HQ.

ISO9000 certification granted April 2022 and attached to this notification.

IATF16949 Letter of Compliance granted December 2022, with full IATF16949 Certification planned Q3'23.

Product Impact:

S32K148: 144LQFP 20\*20 and 100LQFP 14\*14

S32K144: 100LQFP 14\*14, 64LQFP 10\*10 and 48LQFP 7\*7

As assembly site expansion was successfully qualified adhering to NXP specifications, NXP is issuing a Final Product Change Notification (PCN) with qualification results.

Please refer to the attached communication package on TFME-T overview, bill of material comparison, and part number marking decoder.

Corresponding ZVEI Delta Qualification Matrix ID: SEM-PA-02, SEM-PA-03, SEM-PA-07, SEM-PA-11 and SEM-PA-18.

#### **Reason**

Qualification of Tongfu Tongke Microelectronics (TFME-T), Nantong, China is required for manufacturing flexibility and customer supply assurance.

#### **Identification of Affected Products**

Top Side Marking

There is no change to orderable part number.

Change in package trace code is explained under 'Remarks' section below.

#### **Product Availability**

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#### **Sample Information**

Samples are available from May 05, 2023

Please refer to customer communication package for sample part numbers.

#### **Production**

Planned first shipment Jul 20, 2023

#### **Anticipated Impact on Form, Fit, Function, Reliability or Quality**

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No Impact on form, fit, function, reliability or quality

#### **Data Sheet Revision**

No impact to existing datasheet

#### **Disposition of Old Products**

Assembly site expansion. No depletion of Inventory required.

#### **Additional information**

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Self qualification: [view online](#)

Additional documents: [view online](#)

#### **Timing and Logistics**

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In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by May 21, 2023.

#### **Remarks**

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The assembly site, among other information, is reflected in the package trace code.

The format for the NXP standard trace code: AWLYYWW is the following:

A=Assembly Site, WL=Wafer Lot, YY=Year, WW=Work Week.

The current assembly site marking for site 1 (NXP-ATKL) is A = Q

The current assembly site marking for site 2 (NXP-ATTJ) is A = CT

The marking for proposed assembly site 3 (TFME-T) is A = VX

#### **Contact and Support**

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For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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NXP Quality Management Team.

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